

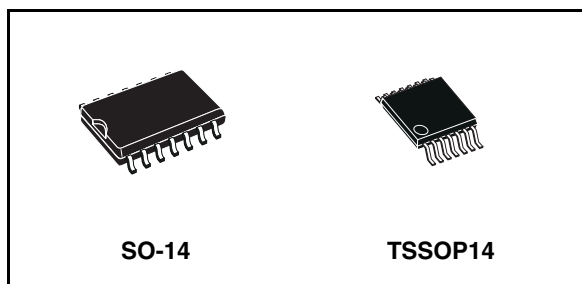


74LCX04

Low voltage CMOS HEX inverter with 5V tolerant inputs

Features

- 5V tolerant inputs
- High speed:
 - $t_{PD} = 5.2\text{ns}$ (Max) at $V_{CC} = 3\text{V}$
- Power down protection on inputs and outputs
- Symmetrical output impedance:
 - $|I_{OH}| = I_{OL} = 24\text{mA}$ (Min) at $V_{CC} = 3\text{V}$
- PCI bus levels guaranteed at 24mA
- Balanced propagation delays:
 - $t_{PLH} \cong t_{PHL}$
- Operating voltage range:
 - V_{CC} (Opr) = 2.0V to 3.6V
- Pin and function compatible with 74 series 04
- Latch-up performance exceeds 500mA (JESD 17)
- ESD performance:
 - HBM > 2000V (MIL STD 883 method 3015); MM > 200V



Description

The 74LCX04 is a low voltage CMOS HEX inverter fabricated with sub-micron silicon gate and double-layer metal wiring C²MOS technology. It is ideal for low power and high speed 3.3V applications. It can be interfaced to 5V signal environment for inputs.

It has same speed performance at 3.3V than 5V AC/ACT family, combined with a lower power consumption.

All inputs and outputs are equipped with protection circuits against static discharge, giving them 2KV ESD immunity and transient excess voltage.

Order codes

Part number	Package	Packaging
74LCX04MTR	SO-14	Tape and reel
74LCX04TTR	TSSOP14	Tape and reel

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1 Logic symbols and I/O equivalent circuit

Figure 1. IEC logic symbols

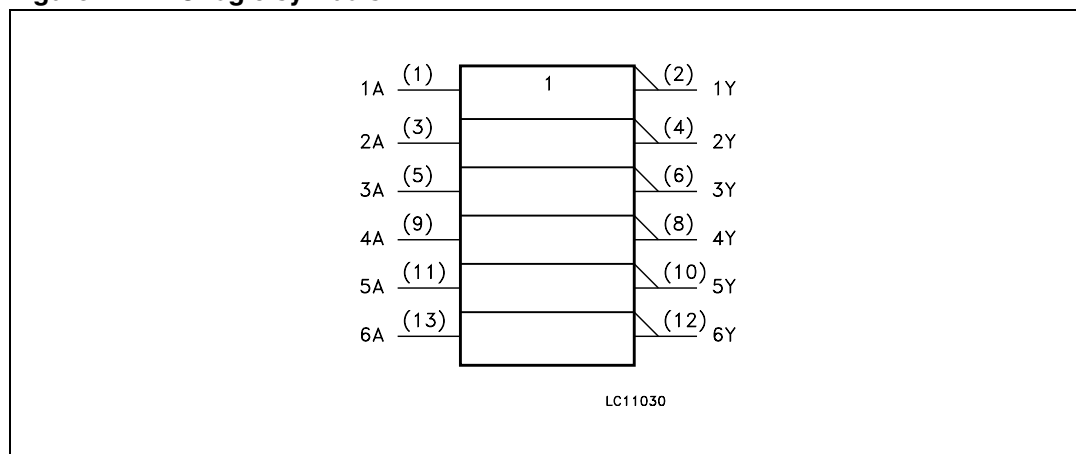
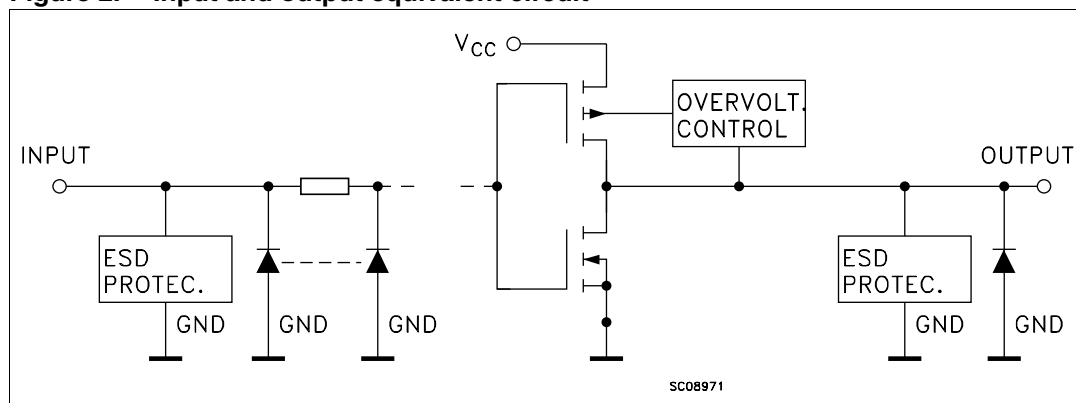


Figure 2. Input and output equivalent circuit



3 Maximum rating

stressing the device above the rating listed in the “absolute maximum ratings” table may cause permanent damage to the device. these are stress ratings only and operation of the device at these or any other conditions above those indicated in the operating sections of this specification is not implied. exposure to absolute maximum rating conditions for extended periods may affect device reliability. refer also to the STMicroelectronics sure program and other relevant quality documents.

Table 3. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{CC}	Supply voltage	-0.5 to +7.0	V
V_I	DC input voltage	-0.5 to +7.0	V
V_O	DC output voltage ($V_{CC} = 0V$)	-0.5 to +7.0	V
V_O	DC output voltage (high or low state) ⁽¹⁾	-0.5 to $V_{CC} + 0.5$	V
I_{IK}	DC input diode current	-50	mA
I_{OK}	DC output diode current ⁽²⁾	-50	mA
I_O	DC output current	± 50	mA
I_{CC}	DC supply current per supply pin	± 100	mA
I_{GND}	DC ground current per supply pin	± 100	mA
T_{stg}	Storage temperature	-65 to +150	°C
T_L	Lead temperature (10 sec)	300	°C

1. I_O absolute maximum rating must be observed

2. $V_O < GND$

3.1 Recommended operating conditions

Table 4. Recommended operating conditions

Symbol	Parameter	Value	Unit
V_{CC}	Supply voltage ⁽¹⁾	2.0 to 3.6	V
V_I	Input voltage	0 to 5.5	V
V_O	Output voltage ($V_{CC} = 0V$)	0 to 5.5	V
V_O	Output voltage (high or low state)	0 to V_{CC}	V
I_{OH}, I_{OL}	High or low level output current ($V_{CC} = 3.0$ to $3.6V$)	± 24	mA
I_{OH}, I_{OL}	High or low level output current ($V_{CC} = 2.7V$)	± 12	mA
T_{op}	Operating temperature	-40 to 85	°C
dt/dv	Input rise and fall time ⁽²⁾	0 to 10	ns/V

1. Truth Table guaranteed: 1.5V to 3.6V

2. V_{IN} from 0.8V to 2V at $V_{CC} = 3.0V$

4 Electrical characteristics

Table 5. DC specifications

Symbol	Parameter	Test condition		Value		Unit
		V _{CC} (V)		-40 to 85°C		
				Min	Max	
V _{IH}	High level input voltage	2.7 to 3.6		2.0		V
V _{IL}	Low level input voltage				0.8	V
V _{OH}	High level output voltage	2.7 to 3.6	I _O =-100 μA	V _{CC} -0.2		V
		2.7	I _O =-12 mA	2.2		
		3.0	I _O =-18 mA	2.4		
			I _O =-24 mA	2.2		
V _{OL}	Low level output voltage	2.7 to 3.6	I _O =100 μA		0.2	V
		2.7	I _O =12 mA		0.4	
		3.0	I _O =16 mA		0.4	
			I _O =24 mA		0.55	
I _I	Input leakage current	2.7 to 3.6	V _I = 0 to 5.5V		±5	μA
I _{off}	Power OFF leakage current	0	V _I or V _O = 5.5V		10	μA
I _{CC}	Quiescent supply current	2.7 to 3.6	V _I = V _{CC} or GND		10	μA
			V _I or V _O = 3.6 to 5.5V		±10	
ΔI _{CC}	I incr. per Input	2.7 to 3.6	V _{IH} = V _{CC} - 0.6V		500	μA

Table 6. Dynamic switching characteristics

Symbol	Parameter	Test condition		Value			Unit
		V _{CC} (V)		T _A = 25 °C			
				Min	Typ	Max	
V _{OLP}	Dynamic low level quiet	3.3	C _L = 50pF V _{IL} = 0V, V _{IH} = 3.3V		0.8		V
V _{OLV}	output ⁽¹⁾				-0.8		

1. Number of outputs defined as "n". Measured with "n-1" outputs switching from HIGH to LOW or LOW to HIGH. The remaining output is measured in the LOW state.

Table 7. AC electrical characteristics

Symbol	Parameter	Test condition				Value		Unit
		V _{CC} (V)	C _L (pF)	R _L (Ω)	t _s = t _r (ns)	-40 to 85 °C		
						Min	Max	
t _{PLH} t _{PHL}	Propagation delay time	2.7	50	500	2.5		6.0	ns
		3.0 to 3.6				1.0	5.2	
t _{OSLH} t _{OSHL}	Output to output skew time ⁽¹⁾ ⁽²⁾	3.0 to 3.6	50	500	2.5		1.0	ns

1. Skew is defined as the absolute value of the difference between the actual propagation delay for any two outputs of the same device switching in the same direction, either HIGH or LOW (t_{OSLH} = |t_{PLHm} - t_{PLHn}|, t_{OSHL} = |t_{PHLm} - t_{PHLn}|)
2. Parameter guaranteed by design

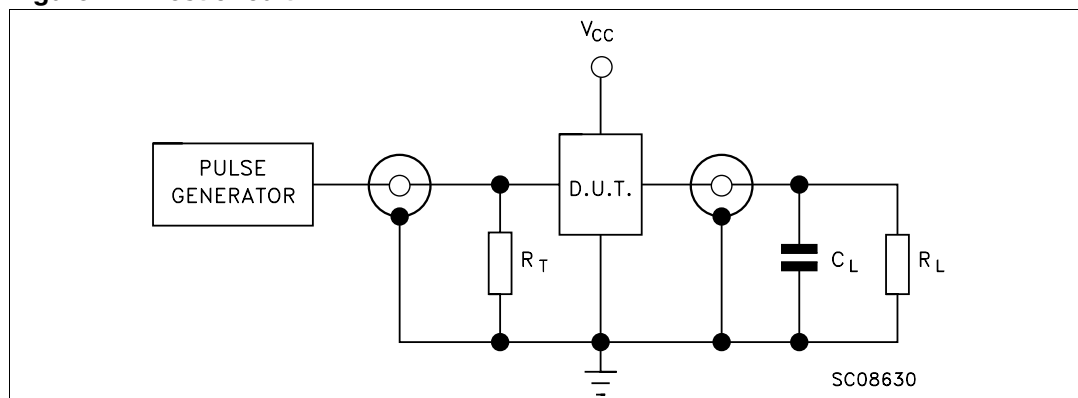
Table 8. Capacitive characteristics

Symbol	Parameter	Test condition		Value			Unit
		V _{CC} (V)		T _A = 25 °C			
				Min	Typ	Max	
C _{IN}	Input capacitance	3.3	V _{IN} = 0 to V _{CC}		5		pF
C _{PD}	Power dissipation capacitance ⁽¹⁾	3.3	f _{IN} = 10MHz V _{IN} = 0 or V _{CC}		41		pF

1. C_{PD} is defined as the value of the IC's internal equivalent capacitance which is calculated from the operating current consumption without load. (Refer to Test Circuit). Average operating current can be obtained by the following equation. I_{CC(opr)} = C_{PD} × V_{CC} × f_{IN} + I_{CC}/6 (per gate)

5 Test circuit

Figure 4. Test circuit



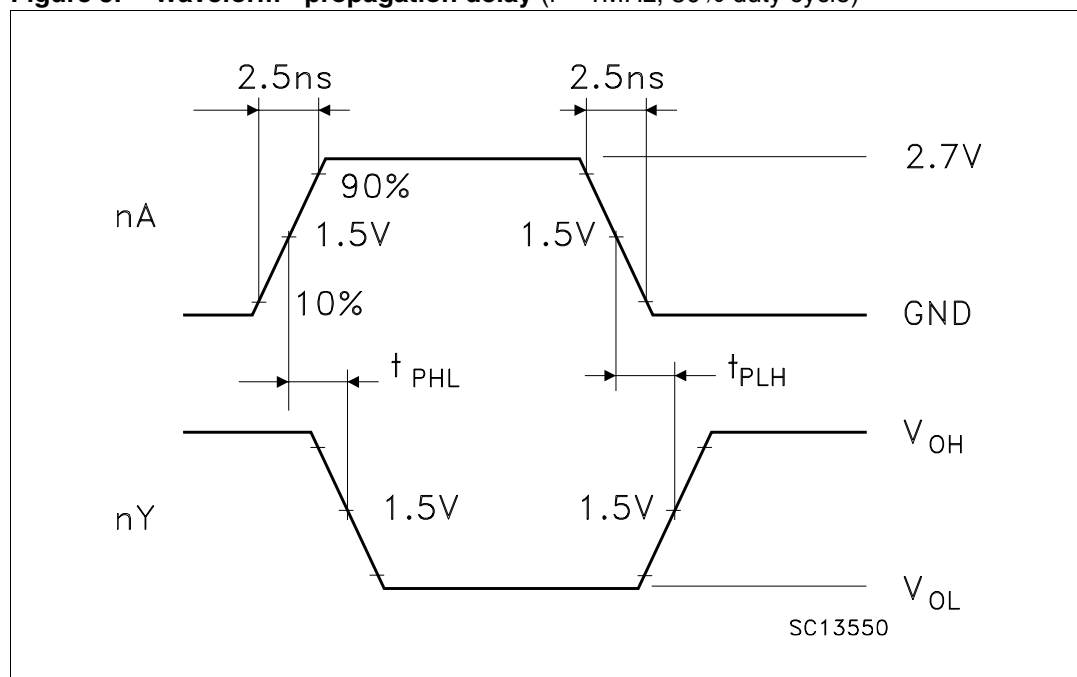
$C_L = 50\text{pF}$ or equivalent (includes jig and probe capacitance)

$R_L = 500\Omega$ or equivalent

$R_T = Z_{OUT}$ of pulse generator (typically 50Ω)

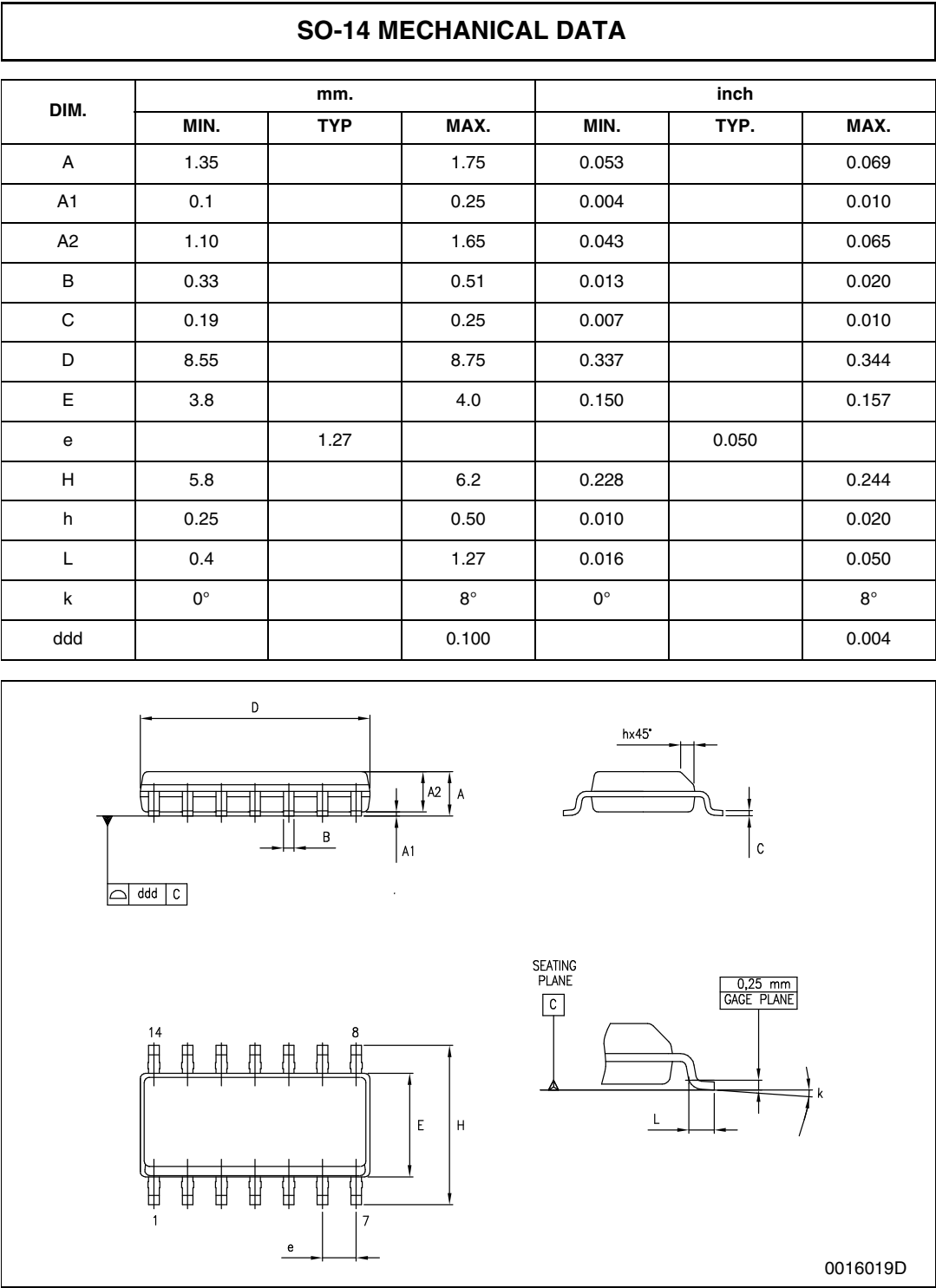
6 Waveforms

Figure 5. Waveform - propagation delay ($f = 1\text{MHz}$; 50% duty cycle)



7 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect . The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com

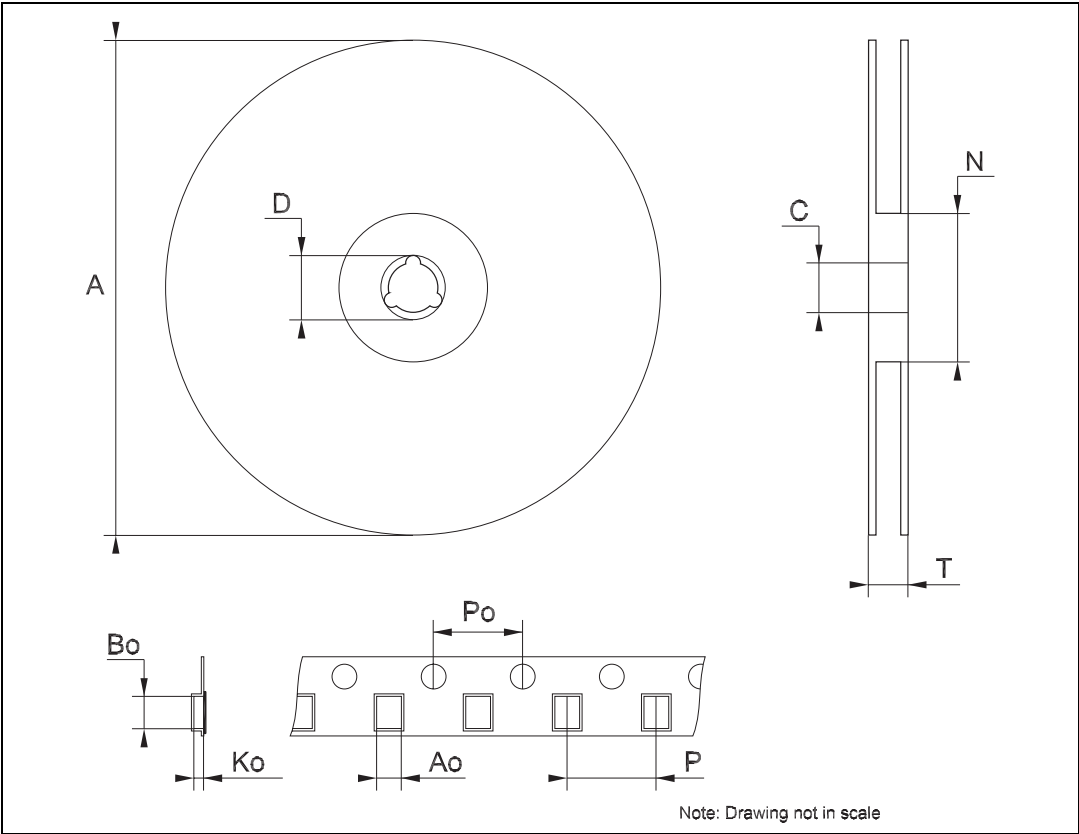


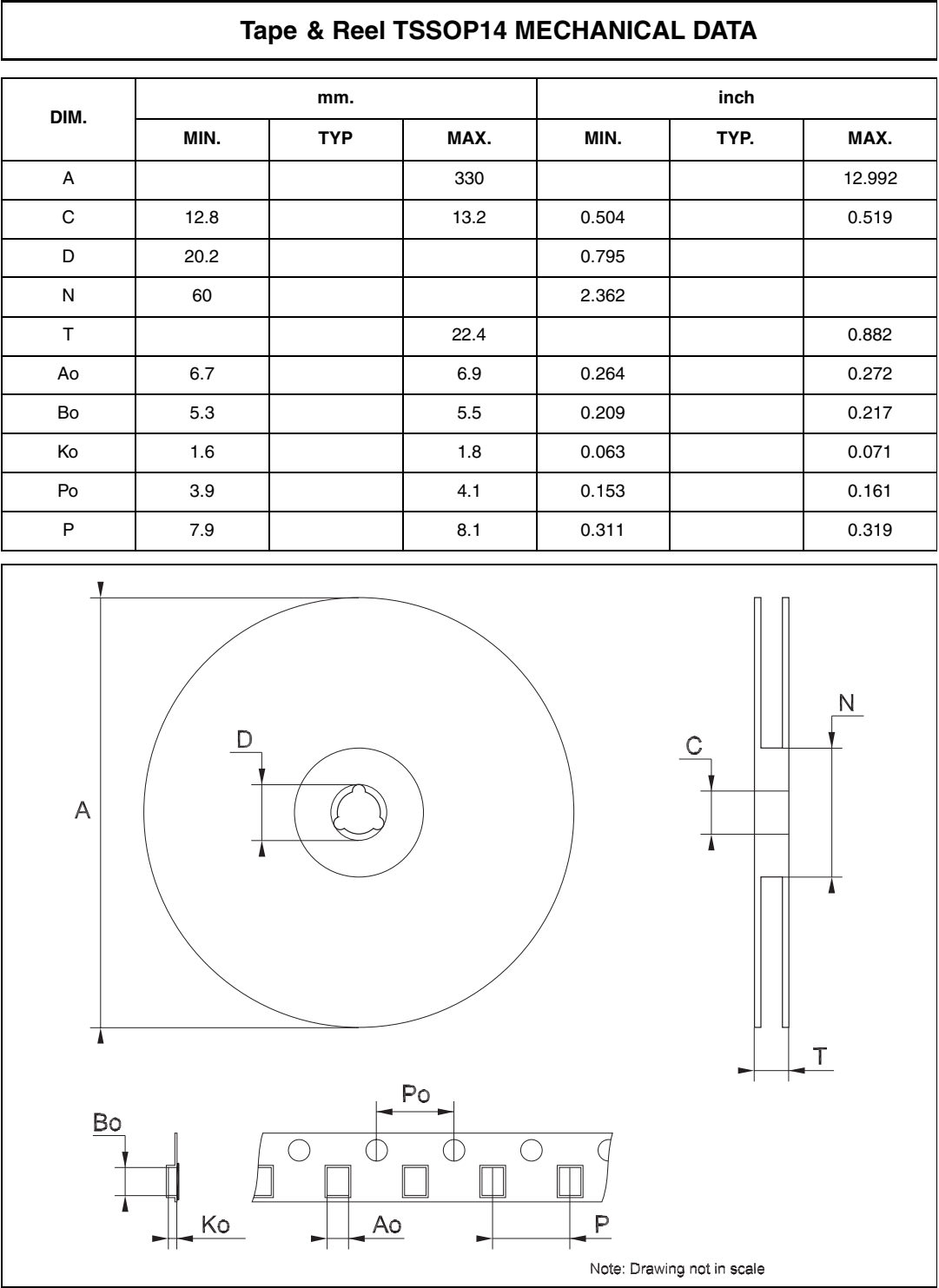
TSSOP14 MECHANICAL DATA						
DIM.	mm.			inch		
	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
A			1.2			0.047
A1	0.05		0.15	0.002	0.004	0.006
A2	0.8	1	1.05	0.031	0.039	0.041
b	0.19		0.30	0.007		0.012
c	0.09		0.20	0.004		0.0089
D	4.9	5	5.1	0.193	0.197	0.201
E	6.2	6.4	6.6	0.244	0.252	0.260
E1	4.3	4.4	4.48	0.169	0.173	0.176
e		0.65 BSC			0.0256 BSC	
K	0°		8°	0°		8°
L	0.45	0.60	0.75	0.018	0.024	0.030

0080337D

Tape & Reel SO-14 MECHANICAL DATA

DIM.	mm.			inch		
	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
A			330			12.992
C	12.8		13.2	0.504		0.519
D	20.2			0.795		
N	60			2.362		
T			22.4			0.882
Ao	6.4		6.6	0.252		0.260
Bo	9		9.2	0.354		0.362
Ko	2.1		2.3	0.082		0.090
Po	3.9		4.1	0.153		0.161
P	7.9		8.1	0.311		0.319





8 Revision history

Table 9. Revision history

Date	Revision	Changes
15-Sep-2004	5	Ordering codes revision - pag. 1.
06-Jul-2006	6	New template, temperature ranges updated

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